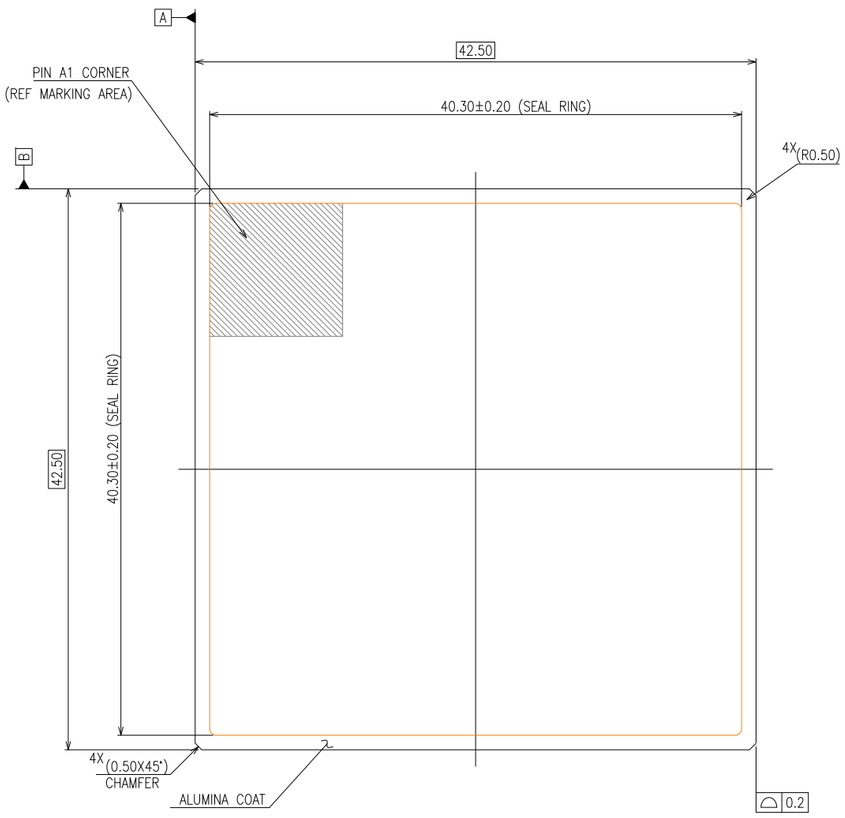
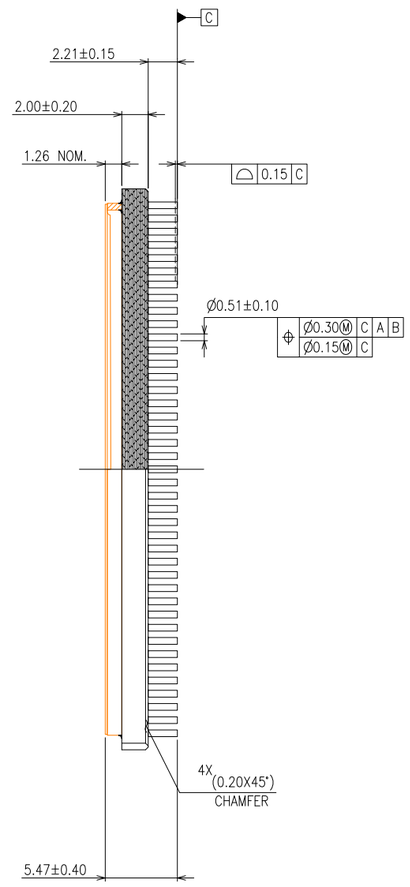
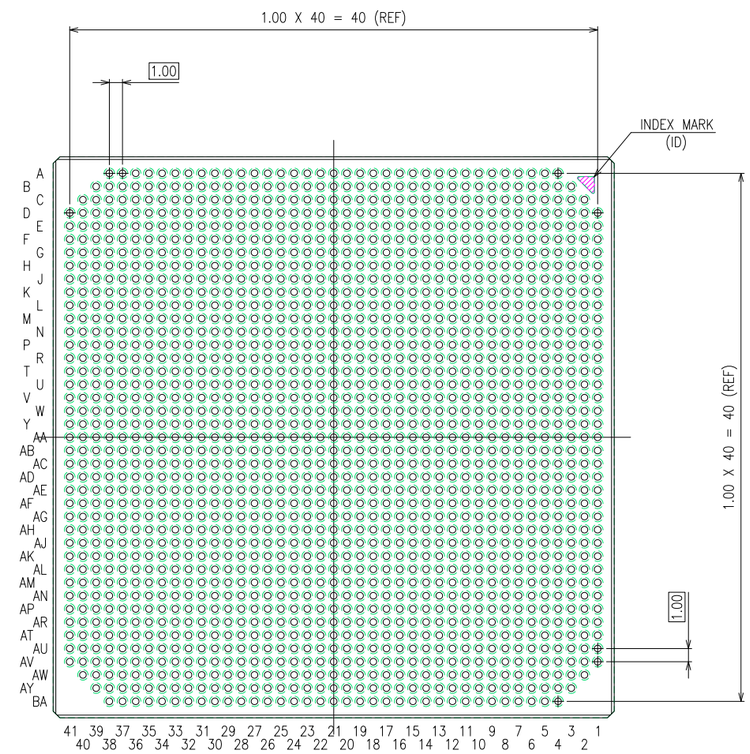
ECN NO.	REV.	DESCRIPTION OF CHANGE	EFFECTIVE DATE	ORIGINATOR
20160067	3	Lid flange thickness change to 0.156 per 1-24-11015	11/12/2015	Lijie Zhao
20160416	4	Delete material info. corrected dimensions.	07/06/2016	Erwin Q.
20160476	5	Add coplanarity specification.	08/11/2016	Erwin Q.







GENERAL TOLERANCE
UNLESS OTHERWISE INDICATED

DECIMAL	ANGULAR
±0.20	±1°

PROJECTION

APPROVALS	DATE
DRAWN: Erwin Quiobo	08/11/2016
CHECKED: Raymond Kuang	08/11/2016
ENG'R:	
RELEASED:	

DIMENSIONS: Millimeters (mm)

Microsemi®

MICROSEMI CORPORATION, SOC GROUP
3850 N 1st St
San Jose, CA 95134

TITLE
CG1657, 42.5 MM X 42.5 MM, 1.0 MM PITCH, 1657 SOLDER COLUMNS
FLIP CHIP, CERAMIC COLUMN GRID ARRAY, PACKAGE OUTLINE DRAWING

MSCC DWG. NUMBER: 1-14-11671		REV 5
VENDOR NAME: KYOCERA	VENDOR DWG. NUMBER: KD-YB5197	REV 0
LID DWG. NUMBER: 1-24-11015	SCALE: N.T.S.	SHEET 1 OF 1

1-06-13016 Rev. 2